



Origami Devices: Design and Application

Guest Editor:

Dr. Shao-Kang Hung

Department of Mechanical
Engineering, National Chiao
Tung University, Hsinchu 30010,
Taiwan

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Message from the Guest Editor

Dear Colleagues,

Paper was invented about 2000 years ago. Due to its inherent folding ability, origami quickly became popular in several cultures and continued to develop for centuries. Nowadays, thanks to computer aided design and modern laser tools, origami is no longer only an art but also a technology. The transformation of 2D plain paper into 3D devices is intricate yet straightforward. The emerging tools are not only functional and useful, but also very interesting and innovative. Paper-based mechanisms, actuators, manipulators, positioners, robots, and machines have been built in recent years.

In this Special Issue, we invite manuscripts conducting interdisciplinary research from areas of diverse expertise that can promote the further development of origami devices. Contributions related (but not limited) to paper-based actuators, foldable devices, and flexible manipulators are welcome. Furthermore, fundamental theories, dynamics, patterns, as well as fabrication techniques of origami devices are also desirable. Any paper-like thin films are included, too.





Editor-in-Chief

Message from the Editor-in-Chief

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Micromachines Editorial Office
MDPI, St. Alban-Anlage 66
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